- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17
 - ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

These quadruple 2-line to 1-line data selectors/multiplexers are designed for 2-V to 5.5-V V_{CC} operation.

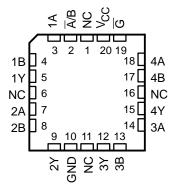
The 'AHC158 devices feature a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. These devices provide inverted data.

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SN54AHC158 J OR W PACKAGE										
SN74AHC158D, DB, DGV, N, NS, OR PW PACKAGE										

((TOP VIEW)												
А/в [1	Ο	16	<u>V</u> cc									
1A [2		15	IJG									
1B [3		14] 4A									
1Y [4		13] 4B									
2A [5		12] 4B] 4Y									
2B [6		11	3A									
2Y [7		10] 3B									
GND [8		9] 3Y									

SN54AHC158 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

т _А	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING								
	PDIP – N	Tube	SN74AHC158N	SN74AHC158N								
	SOIC – D	Tube	SN74AHC158D	AHC158								
	3010 - 0	Tape and reel	SN74AHC158DR	ALICI36								
–40°C to 85°C	SOP – NS	Tape and reel	SN74AHC158NSR	AHC158								
-40 C 10 05 C	SSOP – DB	Tape and reel	SN74AHC158DBR	HA158								
	TSSOP – PW	Tube	SN74AHC158PW	HA158								
	1330F - FW	Tape and reel	SN74AHC158PWR	11A150								
	TVSOP – DGV	Tape and reel	SN74AHC158DGVR	HA158								
	CDIP – J	Tube	SNJ54AHC158J	SNJ54AHC158J								
–55°C to 125°C	CFP – W	Tube	SNJ54AHC158W	SNJ54AHC158W								
	LCCC – FK	Tube	SNJ54AHC158FK	SNJ54AHC158FK								

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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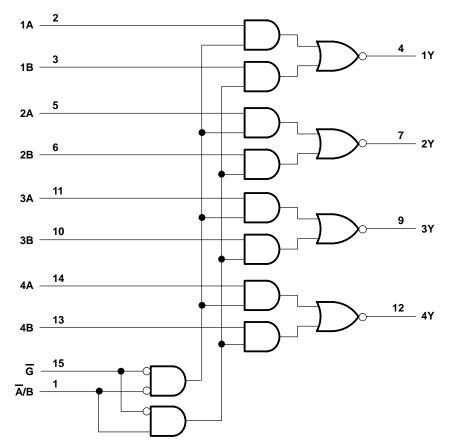


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(FUNCTION TABLE (each data selector/multiplexer)										
	INPU		OUTPUT								
G	A/B	Α	В	Y							
Н	Х	Х	Х	Н							
L	L	L	Х	н							
L	L	Н	Х	L							
L	Н	Х	L	н							
L	Н	Х	Н	L							

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage range, V _I (see Note 1) Output voltage range, V _O (see Note 1) Input clamp current, I _{IK} (V _I < 0) Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) Continuous output current, I _O (V _O = 0 to V _{CC}) Continuous current through V _{CC} or GND Package thermal impedance, θ_{JA} (see Note 2): D	-0.5 V to 7 V -0.5 V to 7 V -0.5 V to 7 V -0.5 V to V _{CC} + 0.5 V -20 mA ±20 mA ±20 mA ±25 mA ±50 mA D package 73°C/W DB package 82°C/W DGV package 67°C/W N package 64°C/W PW package 108°C/W
	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54A	HC158	SN74A	HC158	UNIT	
			MIN	MAX	MIN	MAX	UNIT	
VCC	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
VIH	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V	
		V _{CC} = 5.5 V	3.85		3.85			
		$V_{CC} = 2 V$		0.5		0.5		
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9	V	
		V _{CC} = 5.5 V		1.65		1.65		
VI	Input voltage	0	5.5	0	5.5	V		
VO	Output voltage		0 <	Vcc	0	VCC	V	
		$V_{CC} = 2 V$	(c)	-50		-50	μA	
IOH	High-level output current	V_{CC} = 3.3 V ± 0.3 V	na l	-4		-4	mA	
		V_{CC} = 5 V ± 0.5 V	40	-8		-8		
		V _{CC} = 2 V		50		50	μΑ	
IOL	Low-level output current	V_{CC} = 3.3 V ± 0.3 V		4		4	mA	
		V_{CC} = 5 V ± 0.5 V		8		8	ma	
A+/A.v	logut transition rise or fell rate	V_{CC} = 3.3 V ± 0.3 V		100		100	ns/V	
Δt/Δv	Input transition rise or fall rate	V_{CC} = 5 V ± 0.5 V		20		20	115/ V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	DAMETER	TEST CONDITIONS	N	T _A = 25°C			SN54AHC158		SN74AHC158		UNIT
PARAMETER		TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	2		1.9		1.9		
		I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9		
VOH			4.5 V	4.4	4.5		4.4		4.4		V
		I _{OH} = -4 mA	3 V	2.58			2.48	M:	2.48		
		I _{OH} = -8 mA	4.5 V	3.94			3.8	-M	3.8		
			2 V			0.1	0	0.1		0.1	
		I _{OL} = 50 μA	3 V			0.1	07	0.1		0.1	
VOL			4.5 V			0.1	n_Q	0.1		0.1	V
		I _{OL} = 4 mA	3 V			0.36	PPC	0.5		0.44	
		I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
lj	A or B inputs	VI = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
ICC		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40		40	μA
Ci		V _I = V _{CC} or GND	5 V		2	10				10	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 V$.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	Δ = 25 °	C	SN54A	HC158	SN74A	HC158	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	A or B	Y	Ci - 15 pE		6.2**	9.7**	1**	11.5**	1	11.5	
^t PHL	AUB	I	C _L = 15 pF		6.2**	9.7**	1**	11.5**	1	11.5	ns
^t PLH	Ā/B	Y	Ci - 15 pE		8.4**	13.2**	1**	15.5**	1	15.5	ns
^t PHL	A/B	T	C _L = 15 pF		8.4**	13.2**	1**	15.5**	1	15.5	115
^t PLH	G	Y	C _I = 15 pF		8.7**	13.6**	1**	16**	1	16	ns
^t PHL		I	0L = 10 pi		8.7**	13.6**	1**	16**	1	16	113
^t PLH	A or B	Y	$C_{\rm L} = 50 \rm pE$		8.7	13.2	1	Q 15	1	15	
^t PHL	AOLP	Ť	C _L = 50 pF		8.7	13.2	15	15	1	15	ns
^t PLH		Y	C _I = 50 pF		10.9	16.7	3	19	1	19	ns
^t PHL	Ā/B	r	CL = 50 pr		10.9	16.7	a 1	19	1	19	115
^t PLH	G	Y	C _I = 50 pF		11.2	17.1	1	19.5	1	19.5	ns
^t PHL	G	ſ	CL = 50 pF		11.2	17.1	1	19.5	1	19.5	115

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	Τį	ן = 25°C	;	SN54A	HC158	SN74A	HC158	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
^t PLH	A or B	Y	Ci = 15 pE		4.1*	6.4*	1*	7.5*	1	7.5		
^t PHL	АОГЬ	r	C _L = 15 pF		4.1*	6.4*	1*	7.5*	1	7.5	ns	
^t PLH	Ā/B	V	Ci – 15 pF		5.3*	8.1*	1*	9.5*	1	9.5		
^t PHL	A/B	Y	C _L = 15 pF		5.3*	8.1*	1*	9.5*	1	9.5	ns	
^t PLH	G	Y	0. 15 pF		5.6*	8.6*	1*	10*	1	10		
^t PHL	G	Ť	C _L = 15 pF		5.6*	8.6*	1*	¥10*	1	10	ns	
^t PLH	A or B	Y	$C_{\rm L} = 50 \rm pE$		5.6	8.4	1	9.5	1	9.5	ns	
^t PHL	AUB	I	C _L = 50 pF		5.6	8.4	20	9.5	1	9.5	115	
^t PLH	Ā/B	Y	C _I = 50 pF		6.8	10.1	5	11.5	1	11.5		
^t PLH	A/B	ſ	CL = 50 pF		6.8	10.1	Q 1	11.5	1	11.5	ns	
^t PLH	G	Y	$C_{1} = 50 \text{ pF}$		7.1	10.6	1	12	1	12	ns	
^t PHL	G	ř	C _L = 50 pF		7.1	10.6	1	12	1	12	115	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	SN	UNIT		
		MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V _{OL}			0.8	V
VOL(V)	Quiet output, minimum dynamic V _{OL}			-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}		4.8		V
VIH(D)	High-level dynamic input voltage	3.5			V
V _{IL(D)}	Low-level dynamic input voltage			1.5	V

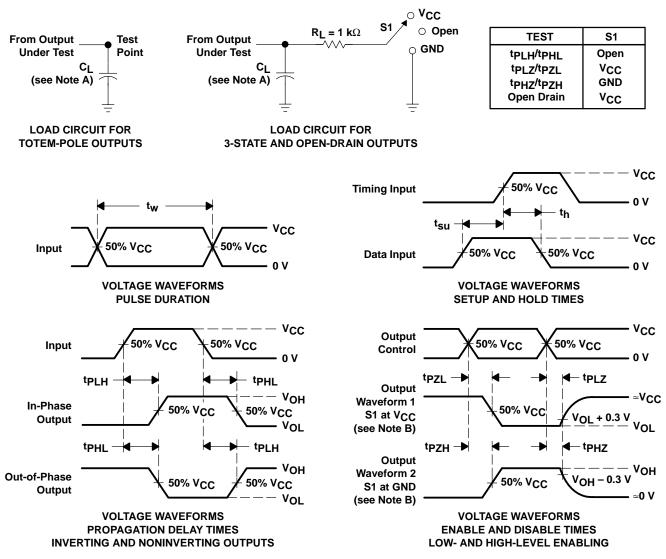
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load,	f = 1 MHz	11	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC158	Samples
SN74AHC158DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA158	Samples
SN74AHC158DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC158	Samples
SN74AHC158N	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHC158N	Samples
SN74AHC158PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA158	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHC158PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

20-Dec-2018



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC158DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AHC158PWR	TSSOP	PW	16	2000	367.0	367.0	35.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW0016A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



PW0016A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PW0016A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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